

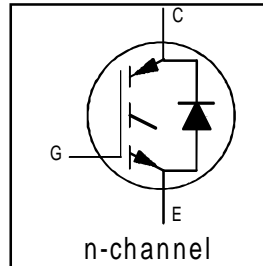
# IRG4RC10SD

INSULATED GATE BIPOLAR TRANSISTOR WITH  
ULTRAFAST SOFT RECOVERY DIODE

Standard Speed CoPack  
IGBT

### Features

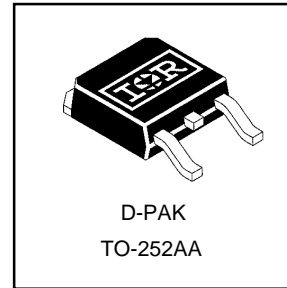
- Extremely low voltage drop 1.1V(typ) @ 2A
- S-Series: Minimizes power dissipation at up to 3 KHz PWM frequency in inverter drives, up to 4 KHz in brushless DC drives.
- Tight parameter distribution
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-252AA package



$V_{CES} = 600V$
$V_{CE(on)} \text{ typ.} = 1.10V$
@ $V_{GE} = 15V, I_C = 2.0A$

### Benefits

- Generation 4 IGBT's offer highest efficiencies available
- IGBT's optimized for specific application conditions
- HEXFRED diodes optimized for performance with IGBT's. Minimized recovery characteristics require less/no snubbing
- Lower losses than MOSFET's conduction and Diode losses



### Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	14	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	8.0	
$I_{CM}$	Pulsed Collector Current ①	18	
$I_{LM}$	Clamped Inductive Load Current ②	18	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	4.0	
$I_{FM}$	Diode Maximum Forward Current	16	
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	V
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	38	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	15	
$T_J$	Operating Junction and	-55 to +150	$^\circ C$
$T_{STG}$	Storage Temperature Range		

### Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	—	3.3	$^\circ C/W$
$R_{\theta JC}$	Junction-to-Case - Diode	—	7.0	
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)*	—	50	
Wt	Weight	0.3 (0.01)	—	g (oz)

\* When mounted on 1" square PCB (FR-4 or G-10 Material).

For recommended footprint and soldering techniques refer to application note #AN-994

# IRG4RC10SD

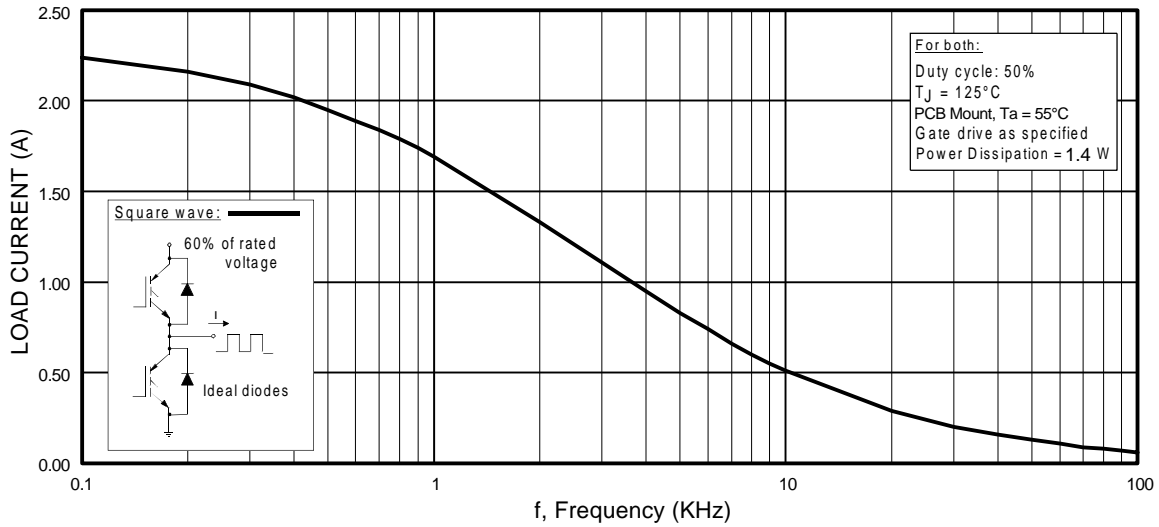
## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage <sup>③</sup>	600	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.64	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	1.58	1.7	V	$V_{GE} = 15V$ See Fig. 2, 5
		—	2.05	—		
		—	1.68	—		
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-9.5	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
$g_{fe}$	Forward Transconductance <sup>④</sup>	3.65	5.48	—	S	$V_{CE} = 100V, I_C = 8.0A$
$I_{CES}$	Zero Gate Voltage Collector Current	—	—	250	$\mu A$	$V_{GE} = 0V, V_{CE} = 600V$ $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$
		—	—	1000		
$V_{FM}$	Diode Forward Voltage Drop	—	1.5	1.8	V	See Fig. 13
		—	1.4	1.7		
$I_{GES}$	Gate-to-Emitter Leakage Current	—	—	$\pm 100$	nA	$V_{GE} = \pm 20V$

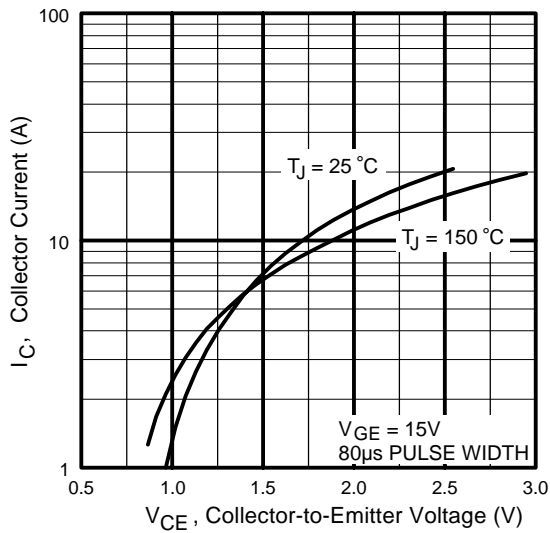
## Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions		
$Q_g$	Total Gate Charge (turn-on)	—	15	22	nC	$I_C = 8.0A$ $V_{CC} = 400V$ $V_{GE} = 15V$ See Fig. 8		
$Q_{ge}$	Gate - Emitter Charge (turn-on)	—	2.42	3.6				
$Q_{gc}$	Gate - Collector Charge (turn-on)	—	6.53	9.8				
$t_{d(on)}$	Turn-On Delay Time	—	76	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 8.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 100\Omega$ Energy losses include "tail" and diode reverse recovery. See Fig. 9, 10, 18		
$t_r$	Rise Time	—	32	—				
$t_{d(off)}$	Turn-Off Delay Time	—	815	1200				
$t_f$	Fall Time	—	720	1080				
$E_{on}$	Turn-On Switching Loss	—	0.31	—				
$E_{off}$	Turn-Off Switching Loss	—	3.28	—				
$E_{ts}$	Total Switching Loss	—	3.60	10.9				
$E_{ts}$	Total Switching Loss	—	1.46	2.6			mJ	$I_C = 5.0A$
$t_{d(on)}$	Turn-On Delay Time	—	70	—			ns	$T_J = 150^\circ\text{C}$ , See Fig. 10,11, 18 $I_C = 8.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 100\Omega$ Energy losses include "tail" and diode reverse recovery.
$t_r$	Rise Time	—	36	—				
$t_{d(off)}$	Turn-Off Delay Time	—	890	—				
$t_f$	Fall Time	—	890	—				
$E_{ts}$	Total Switching Loss	—	3.83	—	mJ			
$L_E$	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package		
$C_{ies}$	Input Capacitance	—	280	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0MHz$ See Fig. 7		
$C_{oes}$	Output Capacitance	—	30	—				
$C_{res}$	Reverse Transfer Capacitance	—	4.0	—				
$t_{rr}$	Diode Reverse Recovery Time	—	28	42			ns	See Fig. 14 $T_J = 125^\circ\text{C}$
		—	38	57				
$I_{rr}$	Diode Peak Reverse Recovery Current	—	2.9	5.2	A	See Fig. 15 $T_J = 125^\circ\text{C}$		
		—	3.7	6.7				
$Q_{rr}$	Diode Reverse Recovery Charge	—	40	60	nC	See Fig. 16 $T_J = 125^\circ\text{C}$		
		—	70	105				
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery During $t_b$	—	280	—	A/ $\mu s$	See Fig. 17 $T_J = 125^\circ\text{C}$		
		—	235	—				

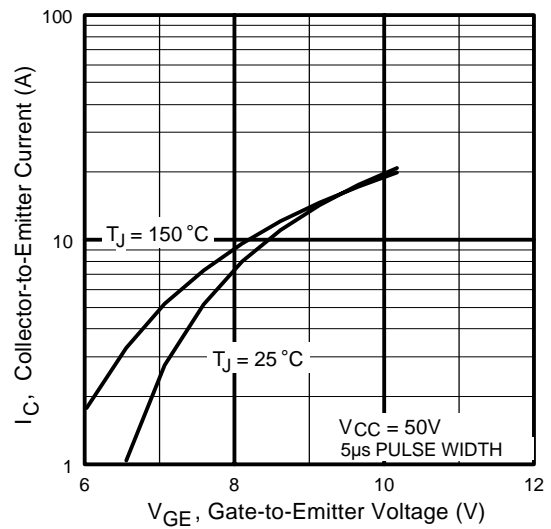
Details of note ① through ④ are on the last page



**Fig. 1 - Typical Load Current vs. Frequency**  
 (Load Current =  $I_{RMS}$  of fundamental)

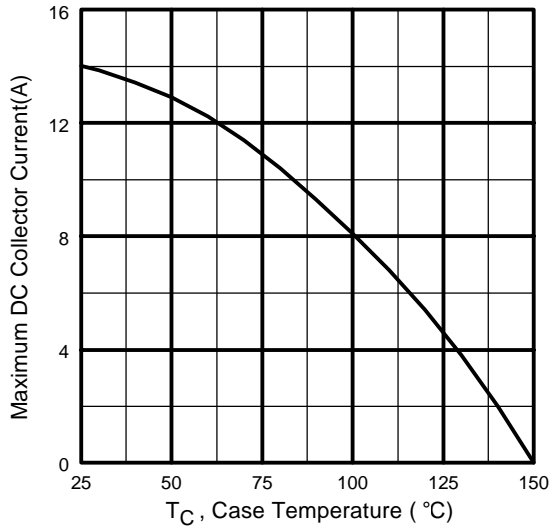


**Fig. 2 - Typical Output Characteristics**

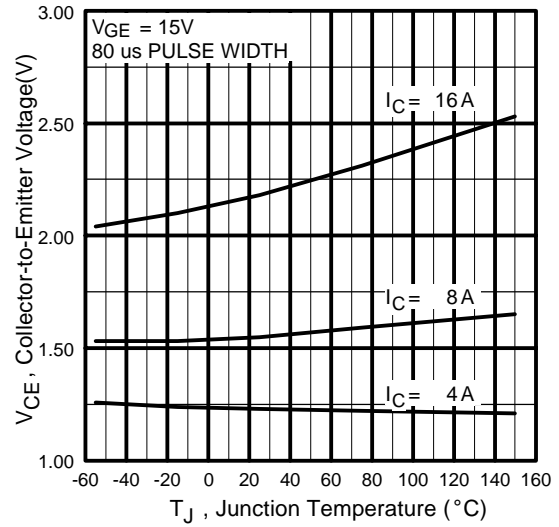


**Fig. 3 - Typical Transfer Characteristics**

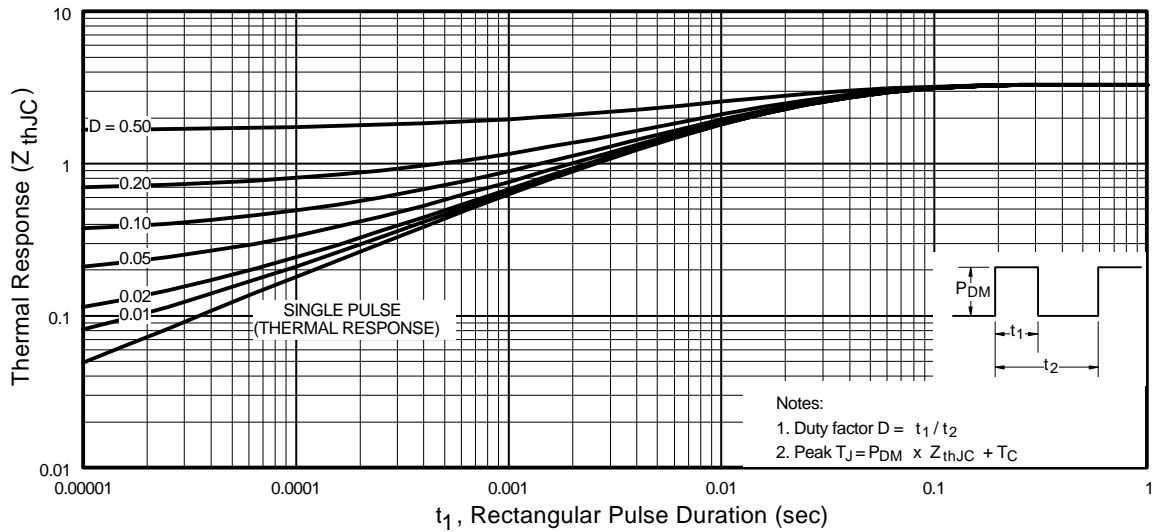
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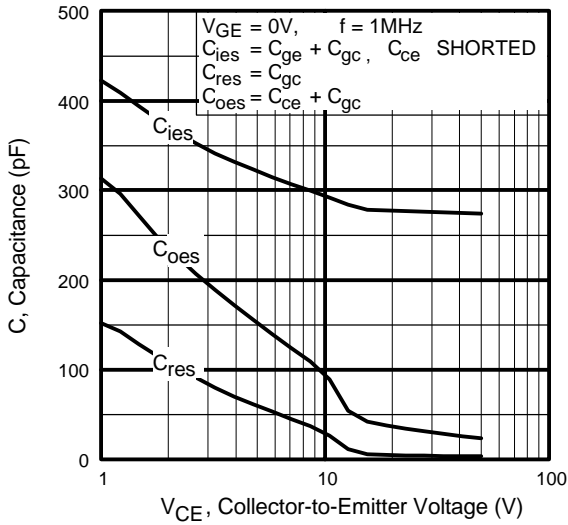
**Fig. 4** - Maximum Collector Current vs. Case Temperature



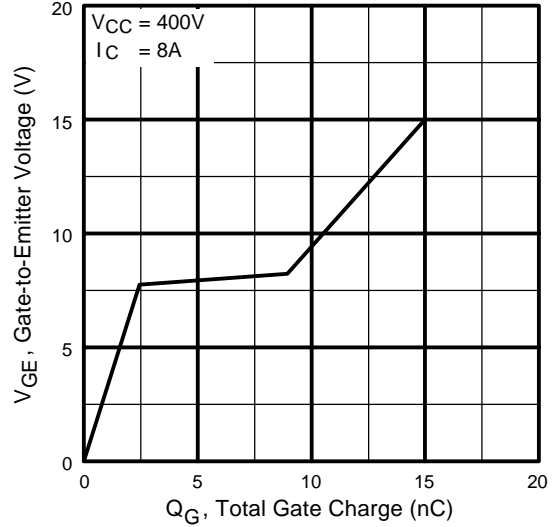
**Fig. 5** - Typical Collector-to-Emitter Voltage vs. Junction Temperature



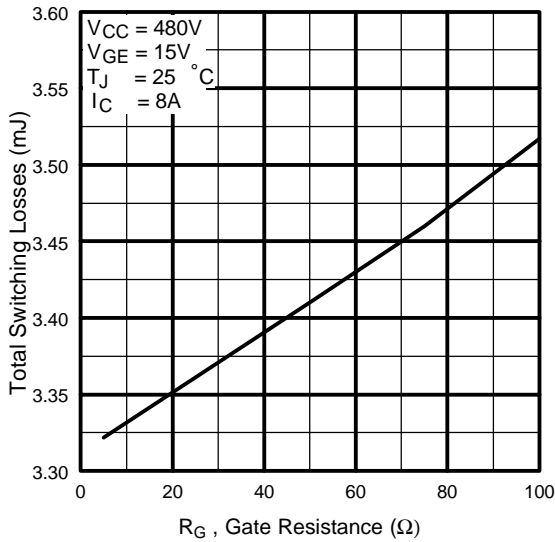
**Fig. 6** - Maximum Effective Transient Thermal Impedance, Junction-to-Case



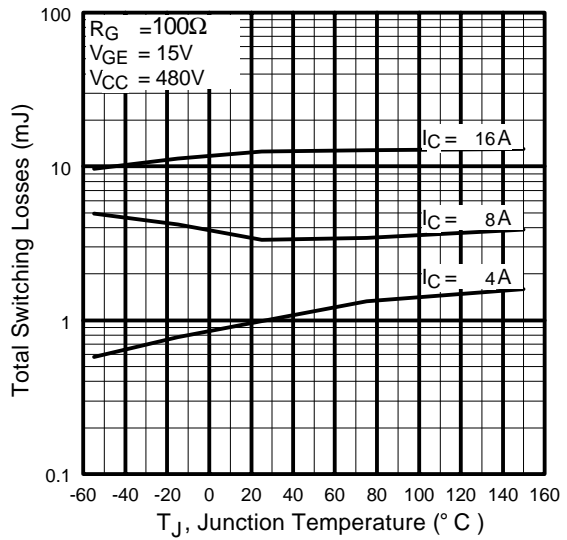
**Fig. 7** - Typical Capacitance vs. Collector-to-Emitter Voltage



**Fig. 8** - Typical Gate Charge vs. Gate-to-Emitter Voltage

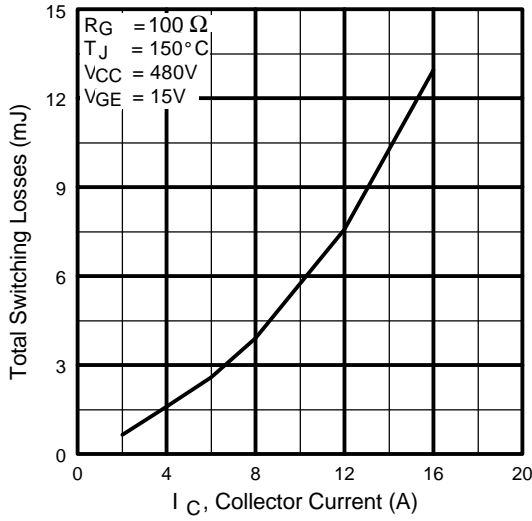


**Fig. 9** - Typical Switching Losses vs. Gate Resistance

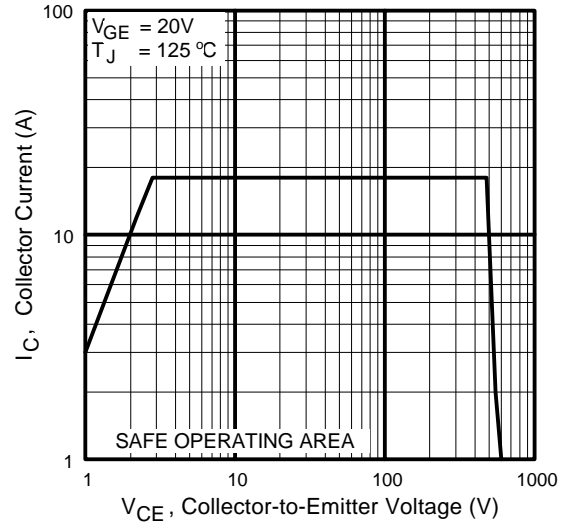


**Fig. 10** - Typical Switching Losses vs. Junction Temperature

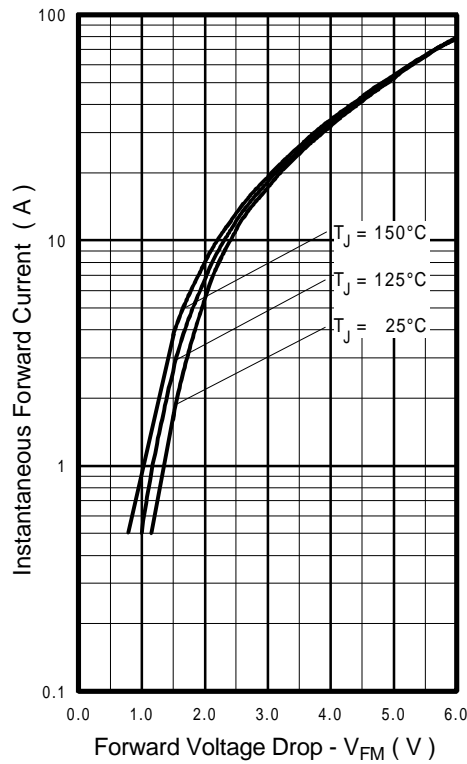
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**Fig. 11** - Typical Switching Losses vs. Collector Current



**Fig. 12** - Turn-Off SOA



**Fig. 13** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

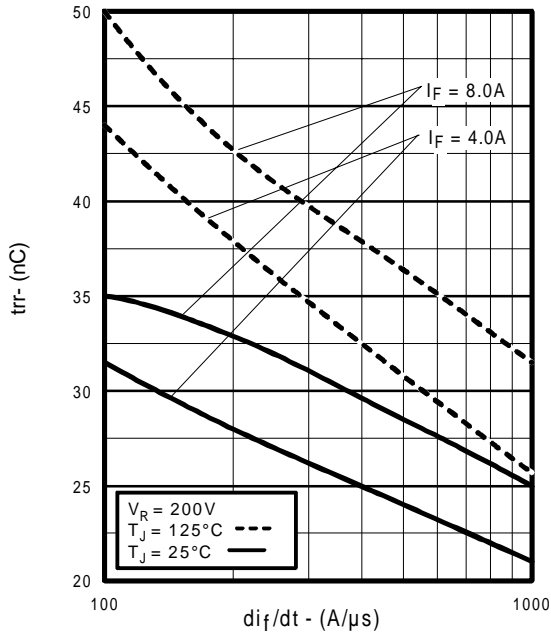


Fig. 14 - Typical Reverse Recovery vs.  $dI_f/dt$

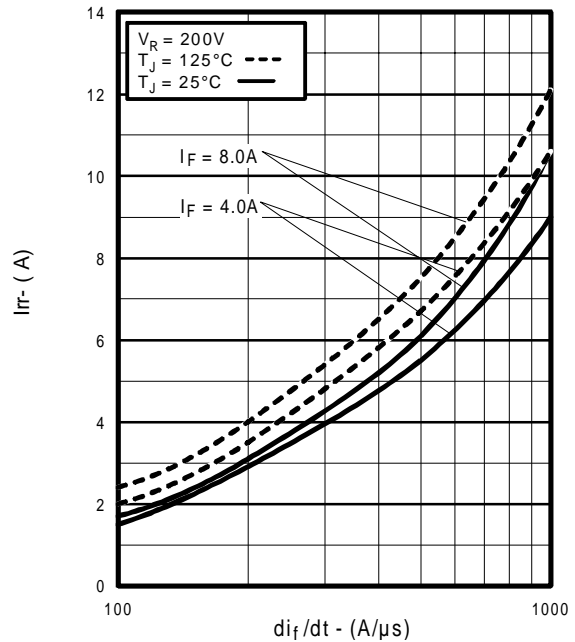


Fig. 15 - Typical Recovery Current vs.  $dI_f/dt$

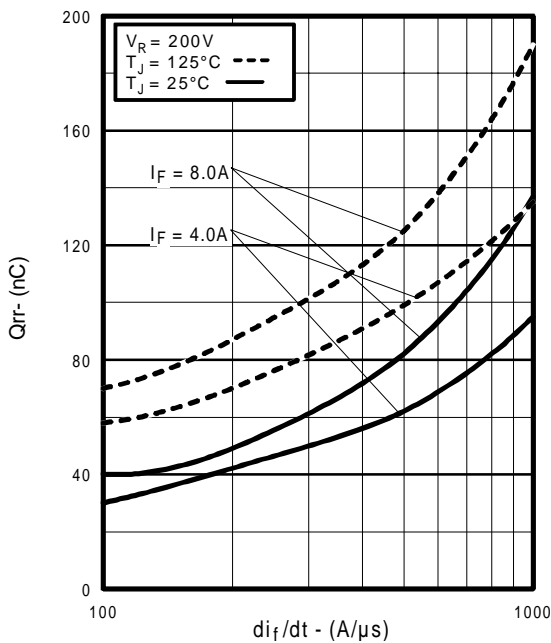


Fig. 16 - Typical Stored Charge vs.  $dI_f/dt$

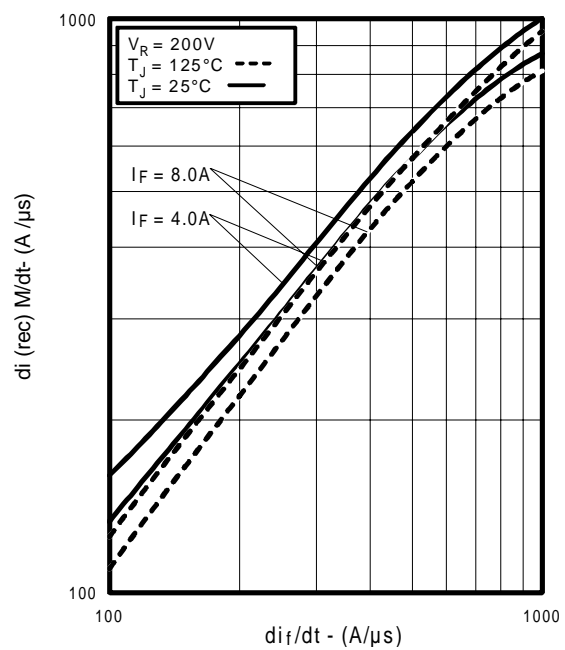
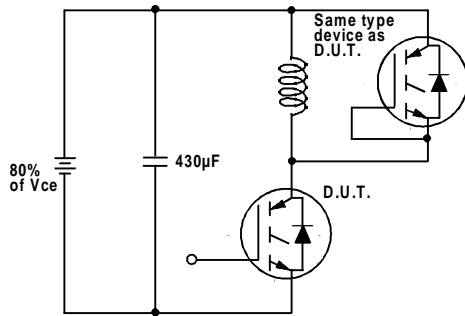
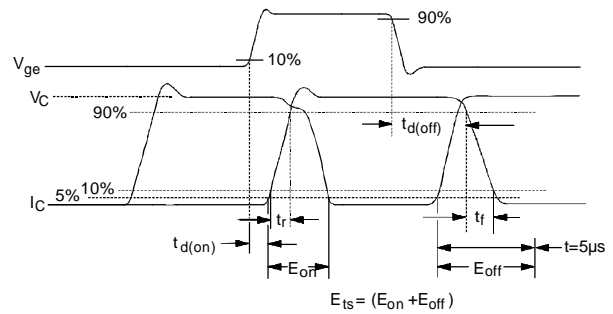


Fig. 17 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_f/dt$ ,

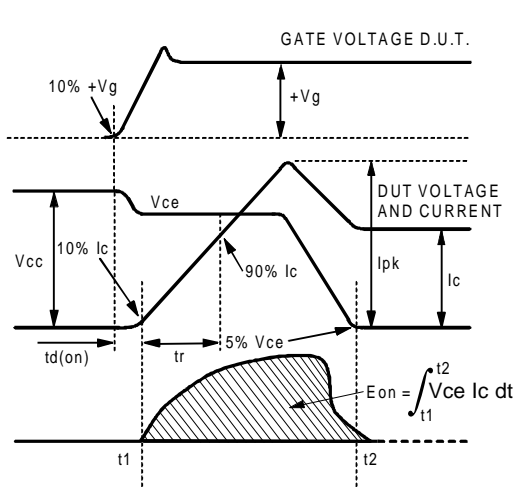
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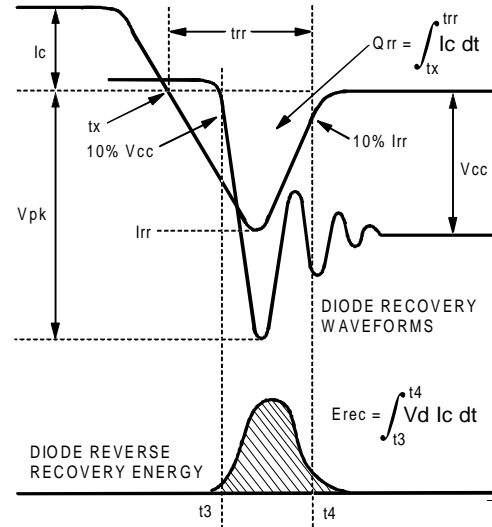
**Fig. 18a** - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off}(\text{diode})$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_{d(on)}$ ,  $t_r$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18b** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18c** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$



**Fig. 18d** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{rec}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$



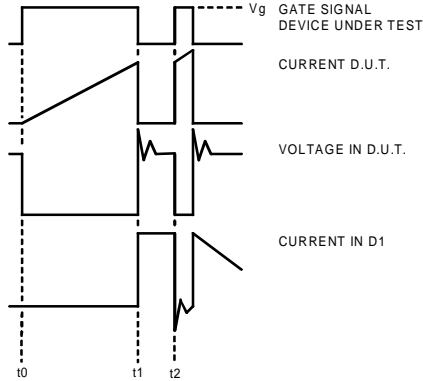


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

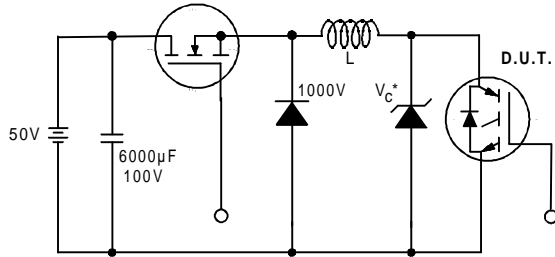


Figure 19. Clamped Inductive Load Test Circuit

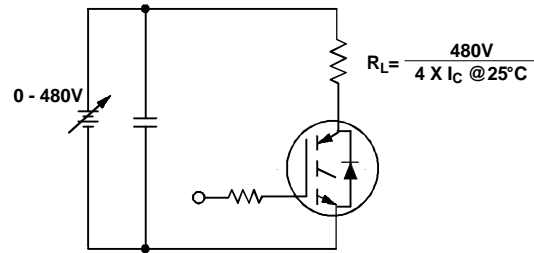
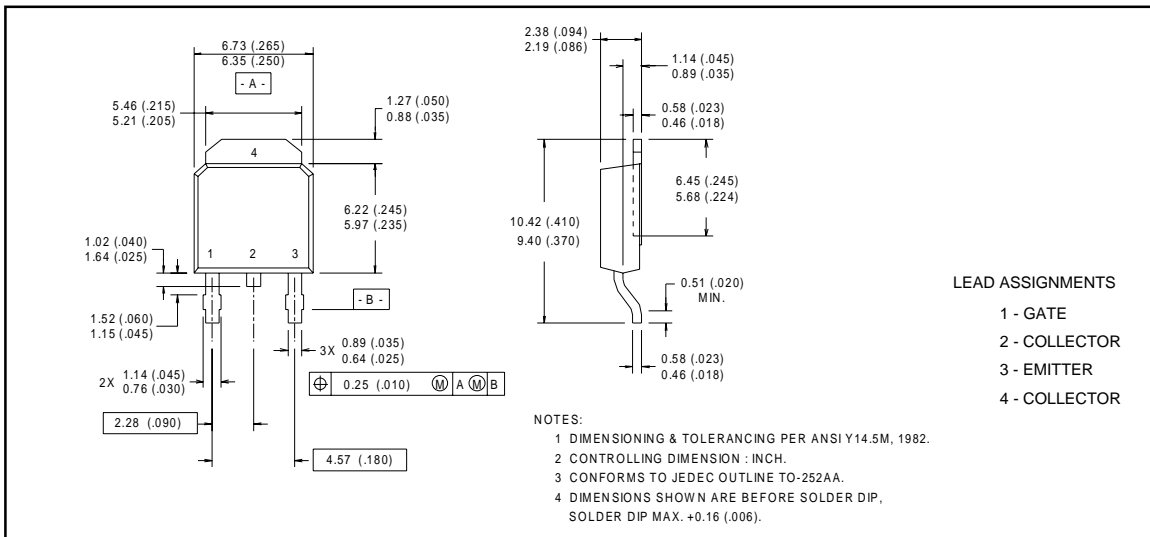


Figure 20. Pulsed Collector Current Test Circuit

## Package Outline

### TO-252AA Outline

Dimensions are shown in millimeters (inches)



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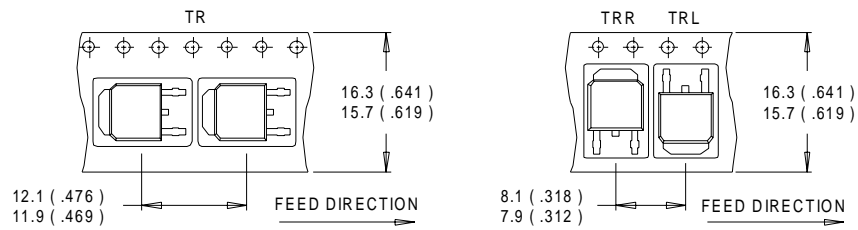
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## Notes:

- ① Repetitive rating:  $V_{GE}=20V$ ; pulse width limited by maximum junction temperature (figure 20)
- ②  $V_{CC}=80\%(V_{CES})$ ,  $V_{GE}=20V$ ,  $L=10\mu H$ ,  $R_G = 100W$  (figure 19)
- ③ Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$ .
- ④ Pulse width  $5.0\mu s$ , single shot.

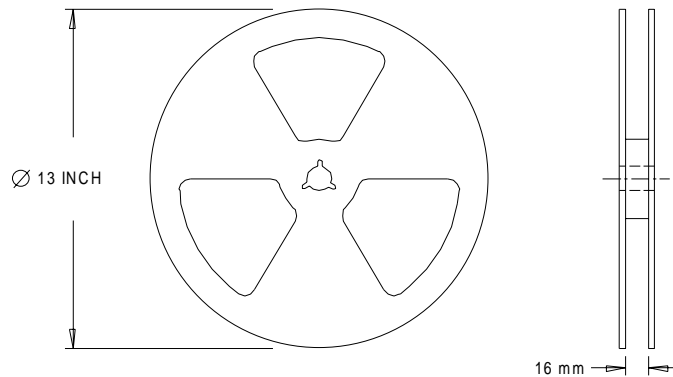
## Tape & Reel Information

### TO-252AA



#### NOTES :

- 1. CONTROLLING DIMENSION : MILLIMETER.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
- 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



#### NOTES :

- 1. OUTLINE CONFORMS TO EIA-481.

International  
**IR** Rectifier

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Data and specifications subject to change without notice. 12/00